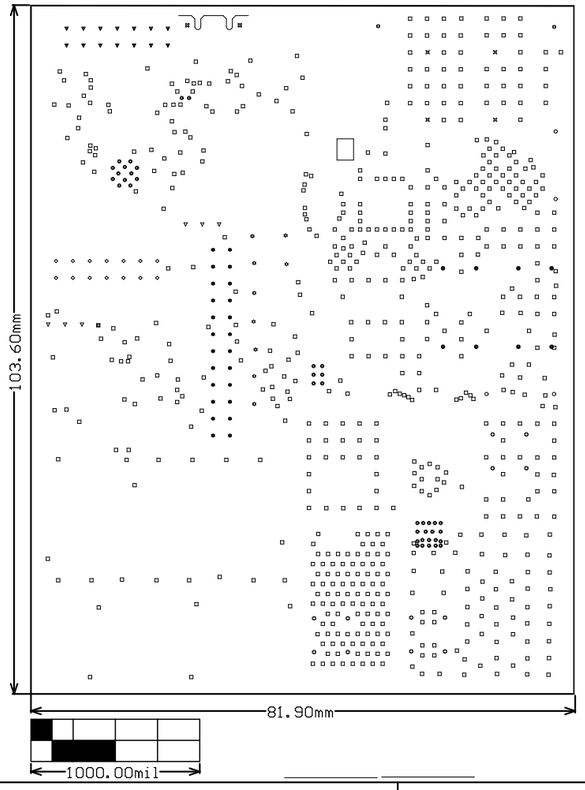
Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◎	39	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
□	644	13.78mil (0.350mm)	PTH	Round	Top Layer - Bottom Layer	
▣	1	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	8	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
◇	14	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
✲	24	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	+/-3.15mil
▽	6	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
▼	14	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	+/-1.97mil
○	4	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	4	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
✪	12	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	+3.94mil/-0.00mil
✡	11	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	783 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		2.80mil		
	Dielectric 1	FR4 370	11.40mil	4.2	
2	Signal Layer 1		1.40mil		
	Dielectric 2	FR4 370	30.00mil	4.2	
3	Signal Layer 2		1.40mil		
	Dielectric 3	FR4 370	11.40mil	4.2	
4	Bottom Layer		2.80mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING: 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENG) [ ] ENEPIG
[ ] MIL TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER MI BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-VO REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL D NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: DRV8263S-H-QIEVM VQFN
DESIGNED FOR: Public Release
FILE NAME: MD0941C1_DRV8263-QIEVM_VQFN.PcbDoc

ENGINEER: Jacob Thompson
LAYOUT BY: Jacob Thompson
SCALE: 1.12
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MD093 | REV: E1 | SVN REV: Not in version control
LAYER NAME = [redacted] | TID #: N/A
PLOT NAME = Fabrication Drawing | GENERATED : 10/1/2024 12:25:55 AM | TEXAS INSTRUMENTS

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